WHAT IS CLAIMED IS:

1. A method of controlling a processing apparatus including a chuck table for holding a workpiece, a processing unit processing the workpiece held on the chuck table, an X-axis moving mechanism moving the chuck table and the processing unit relatively to each other in an X-axis direction, a Y-axis moving mechanism moving the chuck table and the processing unit relatively to each other in a Y-axis direction perpendicular to the X-axis direction, an image capturing unit capturing an image of the workpiece held on the chuck table, a rotating mechanism rotating the chuck table in a plane defined by an X-axis and a Y-axis, a control unit controlling at least the X-axis moving mechanism, the Y-axis moving mechanism, and the rotating mechanism, and display means connected to the control unit for communication therewith, for displaying an image of a portion of the workpiece captured by the image capturing unit and detecting coordinates of a position touched on the display means by an operator,

the method comprising:

operating the X-axis moving mechanism to move the chuck table or the processing unit in the X-axis direction for a distance depending on a distance that a

finger is moved when the operator touches the display means with the finger and moves the finger in the X-axis direction, and moving the image of the portion of the workpiece captured by the image capturing unit in the X-axis direction on the display means;

operating the Y-axis moving mechanism to move the chuck table or the processing unit in the Y-axis direction for a distance depending on a distance that a finger is moved when the operator touches the display means with the finger and moves the finger in the Y-axis direction, and moving the image of the portion of the workpiece captured by the image capturing unit in the Y-axis direction on the display means;

operating the X-axis moving mechanism and the Y-axis moving mechanism to move the chuck table or the processing unit in the oblique direction for a distance depending on a distance that a finger is moved when the operator touches the display means with the finger and moves the finger in a direction oblique to the X-axis direction and the Y-axis direction, and moving the image of the portion of the workpiece captured by the image capturing unit in the oblique direction on the display means; and

operating the rotating mechanism to rotate the

chuck table for a distance depending on a distance that a finger is moved when the operator touches the display means with the finger and moves the finger in a rotating direction, and rotating the image of the portion of the workpiece captured by the image capturing unit on the display means

wherein the workpiece includes a wafer having a plurality of devices formed on a face side thereof in respective areas that are demarcated by a plurality of intersecting projected dicing lines, and

the method further comprises:

bringing a position where the finger touches the display means at a first position with respect to one of the projected dicing lines in the Y-axis direction after the wafer displayed on the display means is moved and the projected dicing lines on the wafer are positioned parallel to the X-axis direction, and displaying a first straight line over a straight-edge region of the one of the projected dicing lines which is detected first;

then moving the position where the finger touches the display means in the Y-axis direction to a second position that is within the projected dicing line, and displaying a second straight line over a straight-edge region of the projected dicing line which is detected

next; and

detecting a region sandwiched between the first straight line and the second straight line as a projected dicing line.

2. The method of controlling a processing apparatus according to claim 1, further comprising:

detecting two adjacent ones of the projected dicing lines and calculating a distance between the two adjacent projected dicing lines.

3. A method of controlling a processing apparatus including a chuck table for holding a workpiece, a processing unit processing the workpiece held on the chuck table, an X-axis moving mechanism moving the chuck table and the processing unit relatively to each other in an X-axis direction, a Y-axis moving mechanism moving the chuck table and the processing unit relatively to each other in a Y-axis direction perpendicular to the X-axis direction, an image capturing unit capturing an image of the workpiece held on the chuck table, a rotating mechanism rotating the chuck table in a plane defined by an X-axis and a Y-axis, a control unit controlling at least the X-axis moving mechanism, the Y-axis moving mechanism, and the rotating mechanism, and display means connected to the control unit for communication

therewith, for displaying an image of a portion of the workpiece captured by the image capturing unit and detecting coordinates of a position touched on the display means by an operator,

the method comprising:

operating the X-axis moving mechanism to move the chuck table or the processing unit in the X-axis direction for a distance depending on a distance that a finger is moved when the operator touches the display means with the finger and moves the finger in the X-axis direction, and moving the image of the portion of the workpiece captured by the image capturing unit in the X-axis direction on the display means;

operating the Y-axis moving mechanism to move the chuck table or the processing unit in the Y-axis direction for a distance depending on a distance that a finger is moved when the operator touches the display means with the finger and moves the finger in the Y-axis direction, and moving the image of the portion of the workpiece captured by the image capturing unit in the Y-axis direction on the display means;

operating the X-axis moving mechanism and the Y-axis moving mechanism to move the chuck table or the processing unit in the oblique direction for a distance

depending on a distance that a finger is moved when the operator touches the display means with the finger and moves the finger in a direction oblique to the X-axis direction and the Y-axis direction, and moving the image of the portion of the workpiece captured by the image capturing unit in the oblique direction on the display means; and

operating the rotating mechanism to rotate the chuck table for a distance depending on a distance that a finger is moved when the operator touches the display means with the finger and moves the finger in a rotating direction, and rotating the image of the portion of the workpiece captured by the image capturing unit on the display means

wherein the workpiece includes a wafer having a plurality of devices formed on a face side thereof in respective areas that are demarcated by a plurality of intersecting projected dicing lines, and

the method further comprises:

displaying a first reference line and a second reference line that initiate from one of the projected dicing lines on both sides of the one of the projected dicing lines in the Y-axis direction when the operator touches the display means and positions the projected

dicing lines on the wafer parallel to the X-axis direction;

indexing-feeding the wafer in the Y-axis direction for a distance depending on a pre-registered distance between adjacent ones of the projected dicing lines when the operator touches the display means and moves the image of the portion of the workpiece captured by the image capturing unit in the Y-axis direction; and

checking if the distance between the adjacent projected dicing lines is proper or not depending on whether the first reference line and the second reference line are superposed on a second projected dicing line on the wafer that is indexing-fed.